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**INITIAL PRODUCT/PROCESS CHANGE NOTIFICATION**  
Generic Copy

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**15-JUL -2005**

**SUBJECT: ON Semiconductor Initial Product/Process Change Notification #14234**

**TITLE: Initial PCN for NLAS4684 ESD Redesign Moving from 0.5u CMOS Process to 0.6u in Tower.**

**EFFECTIVE DATE: 15-Nov-2005**

**AFFECTED CHANGE CATEGORY: Subcontractor Fab Site & Wafer Process**

**AFFECTED PRODUCT DIVISION: Logic Products Div**

**FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:**

Contact Sales Office or Lyle Stewart <RJJ930@onsemi.com>

**NOTIFICATION TYPE:**

Initial Product/Process Change Notification (IPCN)

First change notification sent to customers. IPCNs are issued at least 120 days prior to implementation of the change. An IPCN is advance notification about an upcoming change and contains general information regarding the change details and devices affected. It also contains the preliminary reliability qualification plan.

The completed qualification and characterization data will be included in the Final Product/Process Change Notification (FPCN).

This IPCN notification will be followed by a Final Product/Process Change Notification (FPCN) at least 60 days prior to implementation of the change.

**DESCRIPTION AND PURPOSE:**

This is the Initial Product Change Notification to make customers aware of ESD Improvement Redesign change for NLAS4684 series products. ESD performance is improved to HBM >4000 volts and MM >400 volts. Redesigned from the Tower 0.5 micron CMOS process to the Tower 0.6 micron CMOS process for the benefit of increased electrical performance.

**QUALIFICATION PLAN:**

Reliability Testing required:

1 lot ea. of Bump, QFN 3x3, and Micro-10:

Test	Conditions	Results (#fail/total SS)
PC-Temp Cycle	-65/+150C for 500 cyc	80 pcs

Electrical Characterization: ESD, Latch-up, DC, AC



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**AFFECTED DEVICE LIST (WITHOUT SPECIALS):**

**PART**

NLAS4684FCT1

NLAS4684FCT1G

NLAS4684MNR2

NLAS4684MNR2G

NLAS4684MR2

NLAS4684MR2G